

Approved by:

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SPECIFICATION

MODEL: HD F713A S3 _____

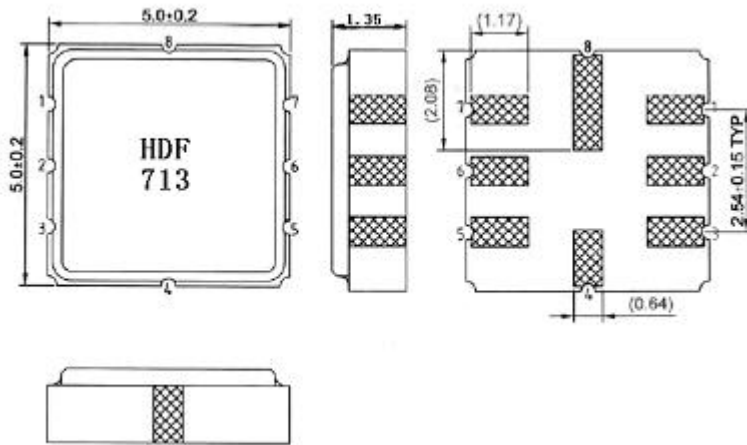
MARKING: HDF 713 _____



SHOULDER ELECTRONIC LIMITED

1. Package Dimension

Unit:mm



NO	Function
2.	Input
1.3	Ground
5.7	Ground
6	Output

2. Marking HD F713

- 2.1 Color: Black or Blue
- 2.2 713: Center Frequency(MHz)

3.Performance

3.1Application

Low-Loss SAW Filter of cordless system.

Center Frequency:713 MHz

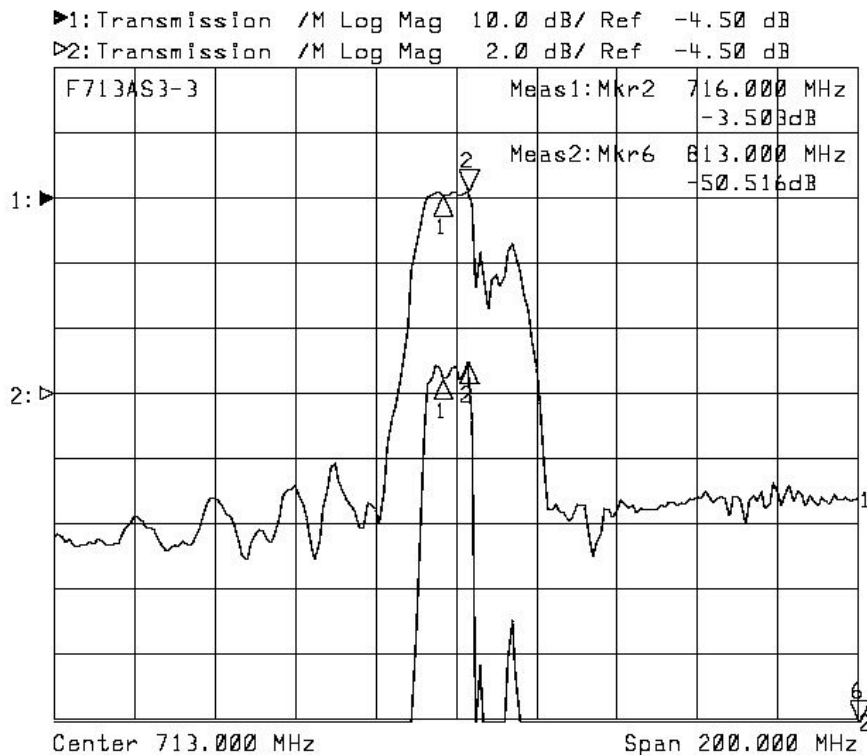
3.2Maximum Rating

Operation Temperature Range	-30°C to +60°C
Storage Temperature Range	-40°Cto +85°C
DC. Voltage	10 V DC. max.
Maximum Input Power	5 dBm

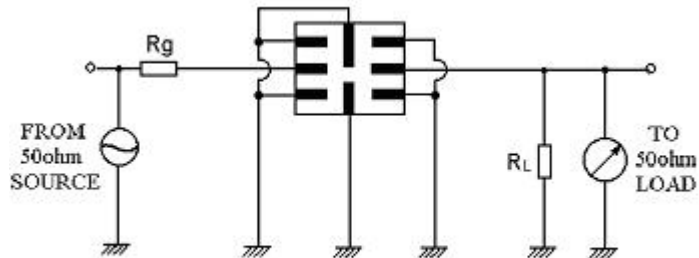
Electronic Characteristics

Part number	F713AS3	Unit
Nominal center frequency (Fo)	713	MHz
Insertion Loss		dB
1.f _o -45.8~f _o -39.8 MHz	45min.	
2.f _o ± 3.0 MHz	4.5max.	
3.f _o +39.8~ f _o +45.8MHz	45min.	
Ripple (with F _o ± 3.0MHz)	2.0max	dB
Input/Output Impedance(Nominal)	50/0	Ω /pF

3.4 Frequency Characteristics



3.5 Test Circuit



4. ENVIRONMENTAL CHARACTERISTICS

4-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+25^{\circ}\text{C}$ for 5 Minutes and a higher temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It

shall meet the specifications in table 1.

4-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in table 1.

4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in table 1.

4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in table 1.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

6. Packing

6.1 Dimensions

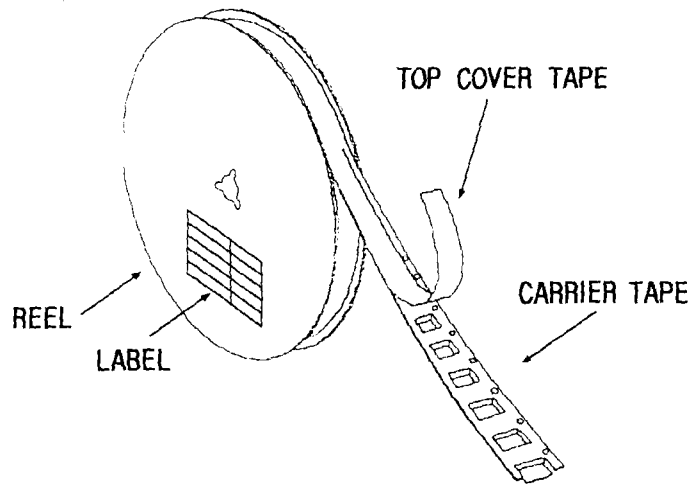
- (1) Carrier Tape: Figure 1
- (2) Reel: Figure 2
- (3) The product shall be packed properly not to be damaged during transportation and storage.

6.2 Reeling Quantity

1000 pcs/reel 7"
3000 pcs/reel 13"

6.3 Taping Structure

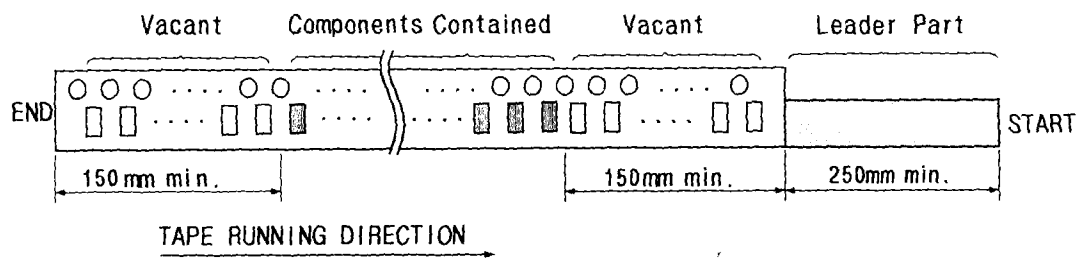
- (1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.



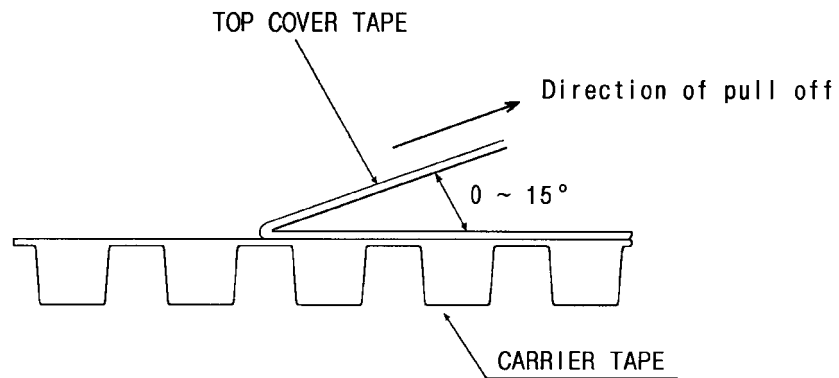
7. TAPE SPECIFICATIONS

7.1 Tensile Strength of Carrier Tape: 4.4N/mm width

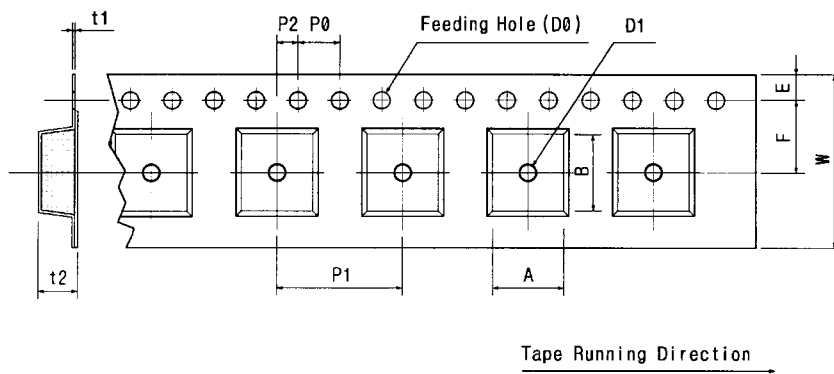
7.2 Top Cover Tape Adhesion (See the below figure)

- (1) pull off angle: 0~15°
- (2) speed: 300mm/min.

(3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

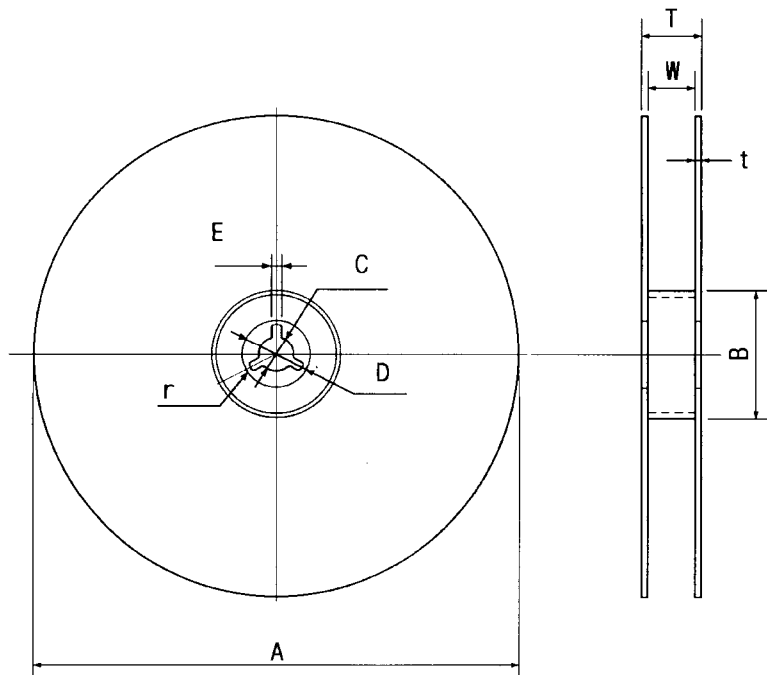


[Unit:mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.0± 0.3	5.5 ±0.05	1.75± 0.1	4.0 ±0.1	8.0 ±0.1	2.0 ±0.05	Ø1.5± 0.1	Ø1.0 ±0.25	0.3 ±0.05	2.10± 0.1	6.40± 0.1	5.20± 0.1

[Figure 2]

[Unit:mm]



A	B	C	D	E	W	t	r
Ø330	Ø100	Ø13	Ø21	2	13	3	1.0
±1.0	±0.5	±0.5	±0.8	±0.5	±0.3	max.	max.